

Report NO.: MG00001000039

1. Product information

Supplier : JIANGSU CHANGJING ELECTRONICS TECHNOLOGY CO.,LTD.

Part Number :	CJB3R0SN10B
Package Type :	TO-263-2L

2. MATERIAL ANALYSIS DATA SHEET

Material	Composition	CAS No.	% of weight	% of weight total
Wafer	Silicon	7440-21-3	100.00%	0.21%
Lead Frame	Ag	7440-22-4	0.01%	
	Phosphorus	7723-14-0	0.04%	
	Iron	7439-89-6	0.15%	
	Copper	7440-50-8	99.80%	
Wire1	Aluminum	7429-90-5	100.00%	3.81%
Wire 2	Copper	7440-50-8	96.55%	
	Gold	7440-57-5	0.35%	
	Palladium	7440/5/3	3.10%	
Soft Solder	Lead	7439-92-1	92.50%	3.30%
	Tin	7440-31-5	5.00%	
	Silver	7440-22-4	2.50%	
Mold Compound	Epoxy Resin A	Trade Secret	5-10%	30.48%
	Epoxy Resin B	29690-82-2	1-5%	
	Phenol Resin	Trade Secret	1-5%	
	Silica(Amorphous) A	60676-86-0	70-90%	
	Silica(Amorphous) B	7631-86-9	5-10%	
	Carbon Black	1333-86-4	0.1-1%	
Plating	Tin	7440-31-5	100.00%	13.65%

Materials Disclosure Disclaimer: Even though all possible efforts have been made to provide you with the information, It is for guidance only and we cannot guarantee to its accuracy or completeness.